



## Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2024-10-28
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	MDG CHAMPION	Representative title	MDGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty statement**

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**Legal statement**

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STM32WB06KCV6TR	F342*F1618B9	A	P1C7	2024-10-28
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	74	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Not Applicable	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy	0	
Package designator	Package size	Number of instances	Shape	
QFN	5x5	32	Flat	
Comment	Package : 42 VFQFPN 5X5x1.0 32L PITCH 0.5 7376875			

QueryList : RoHS Directive 2011/65/EU - 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	
,		

QueryList : REACH-27th June 2024				Response
QUERY				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,	#N/A			



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	F342*F1618B9		74.1378		600000.0	100000.0	
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)	
Die or dies	M-011 Other inorganic materials	7.409	mg	supplier	die	Silicon (Si)	7440-21-3		7.025	mg	948119	94755	
				supplier	metallization	Aluminium (Al)	7429-90-5		0.018	mg	2496	249	
				supplier	metallization	Copper (Cu)	7440-50-8		0.162	mg	21929	2192	
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.053	mg	7131	713	
				supplier	metallization	Titanium (Ti)	7440-32-6		0.003	mg	357	36	
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	178	18	
				supplier	Passivation	Silicon Nitride	12033-89-5		0.041	mg	5527	552	
				supplier	Passivation	Silicon Oxide	7631-86-9		0.106	mg	14263	1425	
				Leadframe (C194)	Copper & its alloys	35.083	mg	supplier	Leadframe	Copper (Cu)	7440-50-8		34.304
supplier	Leadframe	Iron (Fe)	7439-89-6						0.743	mg	21170	10018	
supplier	Leadframe	Zinc (Zn)	7440-66-6						0.034	mg	961	455	
supplier	Leadframe	Phosphorus (P)	7723-14-0						0.002	mg	67	32	
supplier	Leadframe	Copper(Cu)	7440-50-8						0.401	mg	420000	5413	
DAF (CDF 625P12C)	Precious metals	0.956	mg	supplier	Glue or tape	Propenenitrile polymer	68610-41-3		0.072	mg	75000	967	
				supplier	Glue or tape	Epoxy Cresol Novolak	29690-82-2		0.029	mg	30000	387	
				supplier	Glue or tape	Aniline	67784-74-1		0.031	mg	32000	412	
				supplier	Glue or tape	BPADA Imide, extended Bismaleimide	1224691-98-8		0.031	mg	32000	412	
				supplier	Glue or tape	Epon Resin 828	25068-38-6		0.005	mg	5500	71	
					#N/A	Bonding wire	Silver	7440-24-4		0.387	mg	405500	5227
				supplier	Bonding wire	Copper (Cu)	7440-50-8		0.252	mg	990000	3395	
				supplier	Bonding wire	Silver (Ag)	7440-22-4		0.001	mg	2000	7	
Encapsulation (CEL 9240ZH10W)	M-011 Other inorganic materials	30.140	mg	supplier	Bonding wire	Other	Proprietary		0.002	mg	8000	27	
				supplier	Molding Compound	Silica vitreous	60676-86-0		26.524	mg	880000	357761	
				supplier	Molding Compound	Biphenyl epoxy resin	85954-11-6		1.507	mg	50000	20327	
				supplier	Molding Compound	Phenolic resin	205830-20-2		1.175	mg	39000	15855	
				supplier	Molding Compound	Epoxy type resin A	Proprietary		0.603	mg	20000	8131	
				supplier	Molding Compound	Epoxy type resin B	Proprietary		0.271	mg	9000	3659	
				supplier	Molding Compound	Carbon black	1333-86-4		0.060	mg	2000	813	
External Plating (Ni/Pd/Au)	M-011 Other inorganic materials	0.295	mg	supplier	Plating	Nickel (Ni)	7440-02-0		0.271	mg	918364	3659	
				supplier	Plating	Palladium (Pd)	7440-05-3		0.021	mg	69875	278	
				supplier	Plating	Gold (Au)	7440-57-5		0.003	mg	11761	47	